

SELECTING DIE PLACEMENT ON A SEMICONDUCTOR WAFER TO REDUCE TEST TIME

ABSTRACT

A die placement of dies on a wafer is selected to reduce test time of the dies by obtaining a die placement and determining placements of a tester head needed to test the dies in the die placement. A number of touchdowns needed in the determined placements of the tester head is determined, where a touchdown involves lowering the tester head to form an electrical contact between pins on the tester head and bonding pads on a die being tested. The die placement is adjusted to reduce the number of touchdowns.